

Analog Signal Processor RX-IF IC for W-CDMA Cellular Phones

Description

The CXA3328TN/EN is an analog signal processor RX-IF IC for W-CDMA cellular phones. This IC contains a gain control amplifier and quadrature demodulator.

Features

- Wide gain control range
- Linear gain slope
- Wide band (100 to 600MHz)
- Small package
 - 16-pin TSSOP (CXA3328TN)
 - 16-pin VSON (CXA3328EN)
- Low voltage operation (2.7 to 3.3V)

Absolute Maximum Ratings

• Supply voltage	V_{CC}	-0.3 to 5.5	V
• Operating temperature	T_{opr}	-55 to +125	°C
• Storage temperature	T_{stg}	-65 to +150	°C

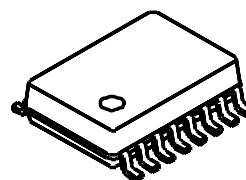
Operating Conditions

• Supply voltage	V_{CC}	2.7 to 3.3	V
• Operating temperature	T_a	-25 to +85	°C

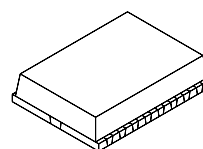
Structure

Bipolar silicon monolithic IC

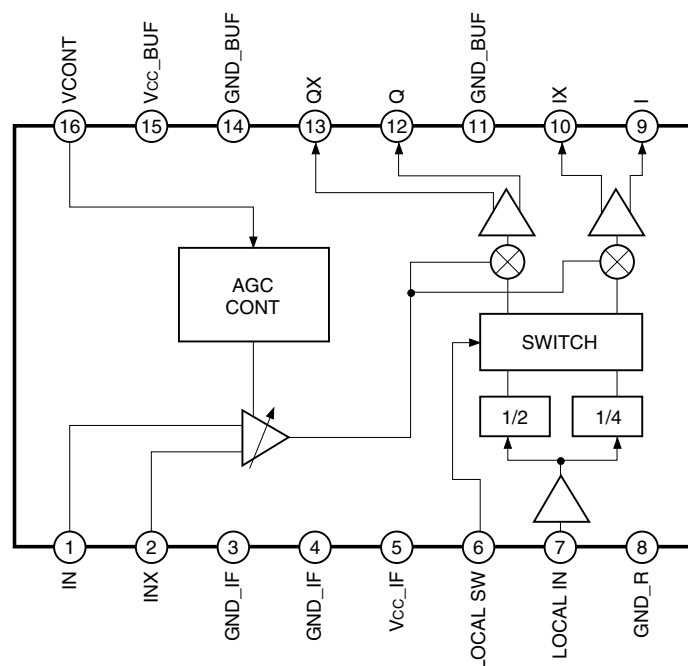
16 pin TSSOP (Plastic)



16 pin VSON (Plastic)



Block Diagram



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Pin Description

Pin No.	Symbol	Typical pin voltage [V]	Equivalent Circuit	Pin Description
1, 2	IN, INX	2.85		IF differential input.
3, 4	GND_IF	0		GCA, quadrature demodulator block ground.
5	Vcc_IF	2.85		GCA, quadrature demodulator block Vcc.
6	LOCAL SW	—		Local frequency division ratio setting. High: 1/4 frequency division Low: 1/2 frequency division
7	LOCAL IN	—		Local input.
8	GND_R	0		Local signal GND.
9, 10, 12, 13	I, IX, Q, QX	1.5		Baseband I, Q outputs.

Pin No.	Symbol	Typical pin voltage [V]	Equivalent Circuit	Pin Description
11, 14	GND_BUF	0		Output buffer block ground.
15	Vcc_BUF	2.85		Output buffer block V _{CC} .
16	VCONT	—		Gain control voltage input.

Electrical Characteristics

Current Consumption

(V_{CC} = 2.85V, Ta = 27°C)

Item	Symbol	Conditions	Measure- ment circuit	Measure- ment point	Min.	Typ.	Max.	Unit
Current Consumption	I _{CC}	V _{cont} = 1.3V	1	A	8	11	15	mA

I/O Resistance

(V_{CC} = 2.85V, Ta = 27°C)

Item	Symbol	Conditions	Measure- ment circuit	Measure- ment point	Min.	Typ.	Max.	Unit
Input resistance VCONT pin	R _{IVC}	DC measurement: V _{IN} = 2.85V	1	B	10	—	—	kΩ
LO input resistance	R _{ILO}	DC measurement: I _{IN} = 2mA	1	C	37.5	50	62.5	Ω
Output resistance I, IX, Q, QX pins	Z _{OUT}	DC measurement: I _{OUT} = 100μA	1	D, E F, G	80	250	550	Ω

IF I/O Resistance (Design Values)

(V_{CC} = 2.85V, Ta = 27°C)

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
IF input resistance	R _{IIF}	Differential between Pins 1 and 2 380MHz	—	2.6	—	kΩ
IF input capacitance	C _{IIF}	Differential between Pins 1 and 2 380MHz	—	2	—	pF

Input Conditions

(V_{CC} = 2.85V, Ta = 27°C)

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
IF input frequency 1	F _{RXIF1}	LOCAL SW = "L"	—	380	—	MHz
IF input frequency 2	F _{RXIF2}	LOCAL SW = "H"	—	190	—	MHz
LO input frequency	F _{LO}		—	760	—	MHz
LO input level	V _{LO}		−18	−15	−12	dBm

GCA Block

(V_{CC} = 2.85V, T_a = 27°C)

Item	Symbol	Conditions	Measure- ment circuit	Measure- ment point	Min.	Typ.	Max.	Unit
Input conversion noise figure	NF	Gain = +65dB	3	A, B C, D	—	—	10	dB
Input conversion 3rd intercept point	IIP3_1	Gain = +65dB F _{RXIF} = 382MHz F _{LO} = 760MHz LOCAL SW = "L"	2	A, B C, D	-58	—	—	dBm
	IIP3_2	Gain = -10dB F _{RXIF} = 382MHz F _{LO} = 760MHz LOCAL SW = "L"	2	A, B C, D	-10	—	—	dBm
Gain flatness	G _F	F _{RXIF} = 382 ± 2.5MHz LOCAL SW = "L" F _{LO} = 2 × (F _{RXIF} + 2) MHz	2	A, B C, D	-0.25	—	0.25	dB
Minimum gain	G _{MIN}	V _{cont} = 0.3 [V], 30mVp-p differential output F _{RXIF} = 382MHz F _{LO} = 760MHz LOCAL SW = "L"	2	A, B C, D	—	-25.5	-20.5	dB
Maximum gain	G _{MAX}	V _{cont} = 2.3 [V], 100mVp-p differential output F _{RXIF} = 382MHz F _{LO} = 760MHz LOCAL SW = "L"	2	A, B C, D	67.5	72.5	—	dB
Gain temperature error	G _{ERR}	T _a = -25 to +85°C	2	A, B C, D	-4	—	4	dB

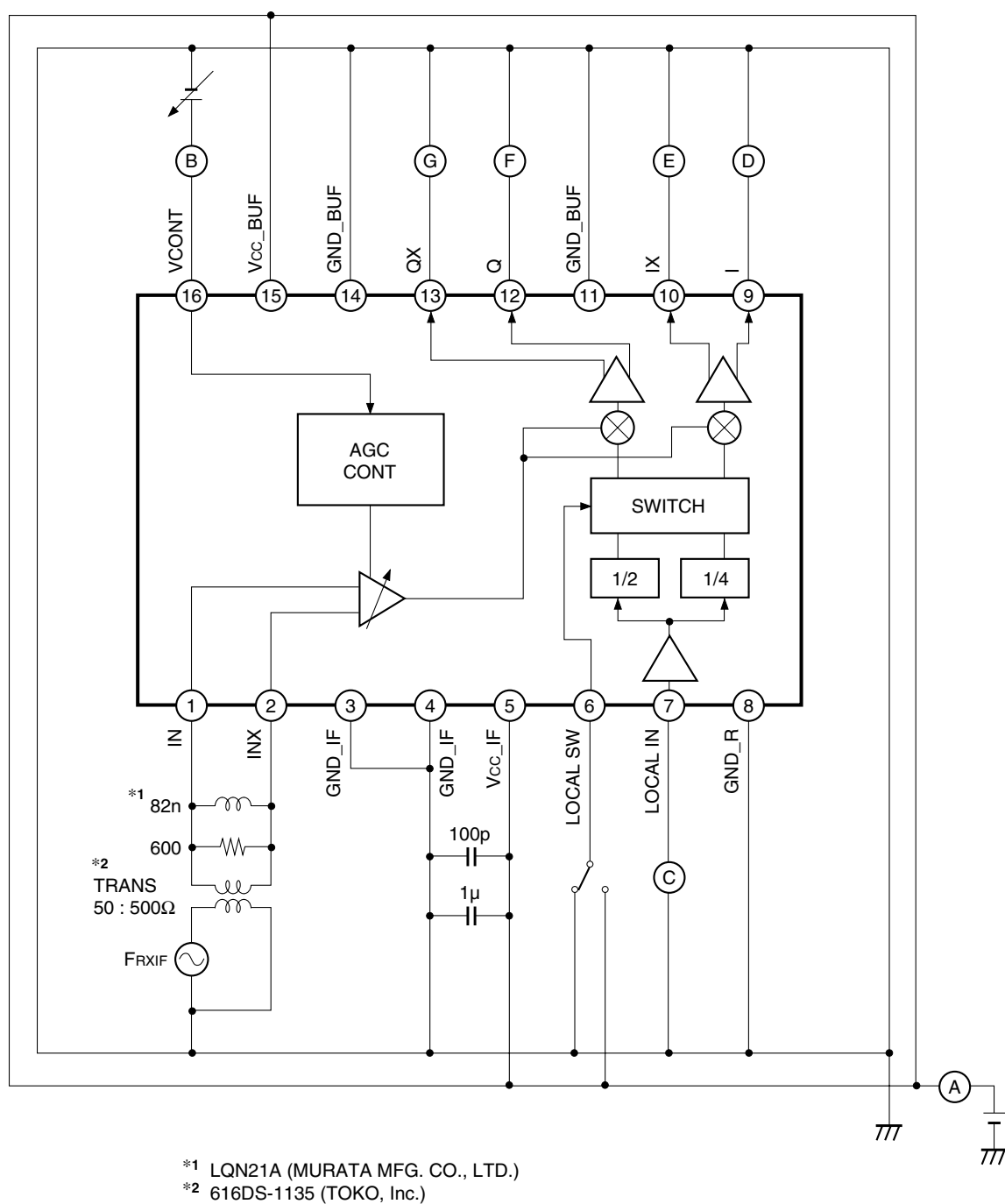
Quadrature Demodulator Block(V_{CC} = 2.85V, T_a = 27°C)

Item	Symbol	Conditions	Measure- ment circuit	Measure- ment point	Min.	Typ.	Max.	Unit
I/Q maximum output amplitude	V _{MAX}	R _L = 10kΩ, C _L = 10pF F _{RXIF} = 382MHz F _{LO} = 760MHz LOCAL SW = "L"	2	A, B C, D	500	—	—	mVp-p
I/Q output band width	V _{BW}	−3dB band width	2	A, B C, D	5	13	—	MHz
I/Q phase error	P _{ERR}	F _{RXIF} = 382MHz F _{LO} = 760MHz LOCAL SW = "L"	2	A, B C, D	−4	—	4	deg
I/Q output amplitude balance	V _{BL}	F _{RXIF} = 382MHz F _{LO} = 760MHz LOCAL SW = "L"	2	A, B C, D	−1.5	—	1.5	dB
I-IX/Q-QX DC offset	V _{OFST}	DC measurement	2	A, B C, D	−200	—	200	mV

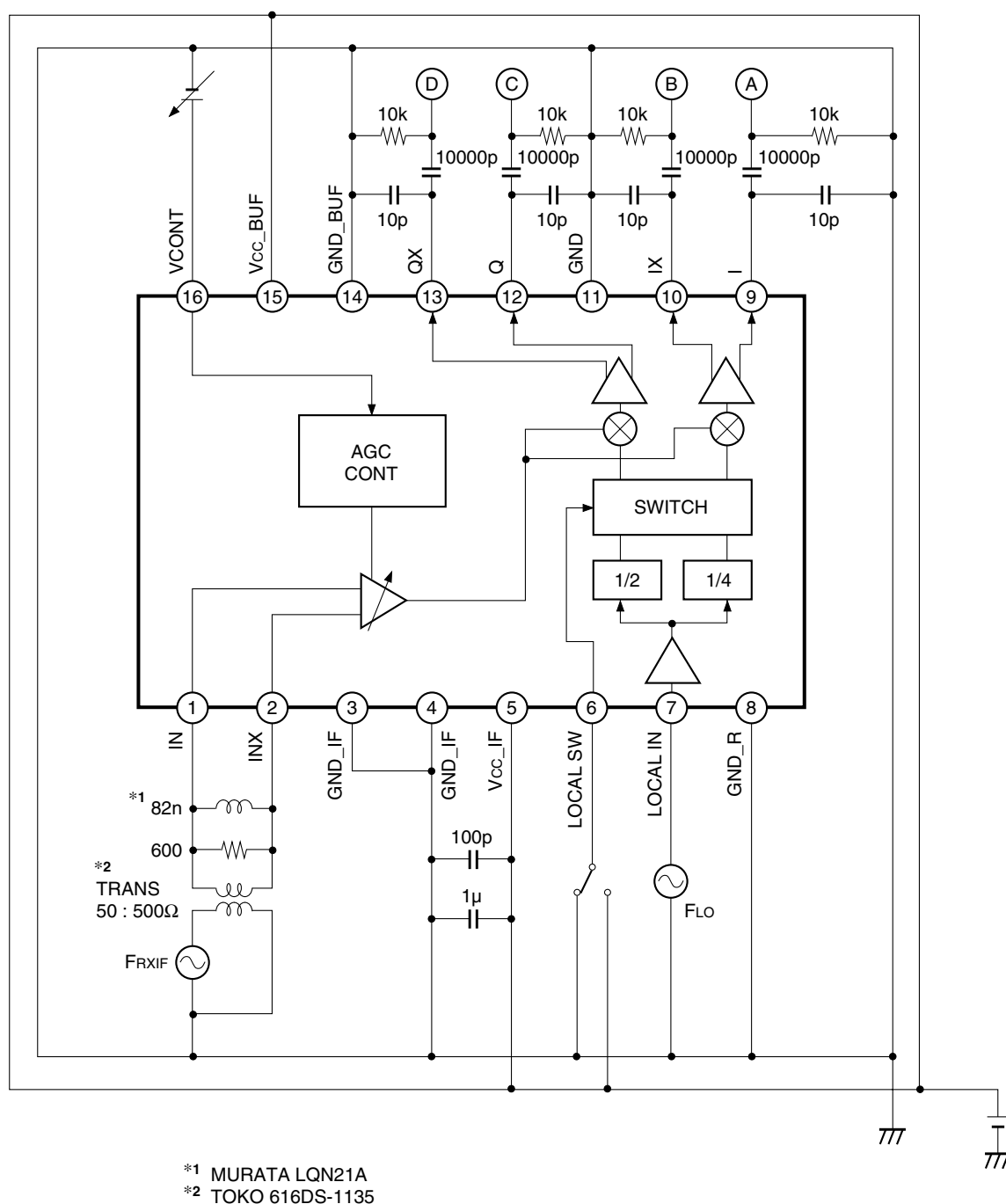
Local Frequency Division Ratio

LOCAL SW (Pin 6)	Frequency division ratio
L	1/2
H	1/4

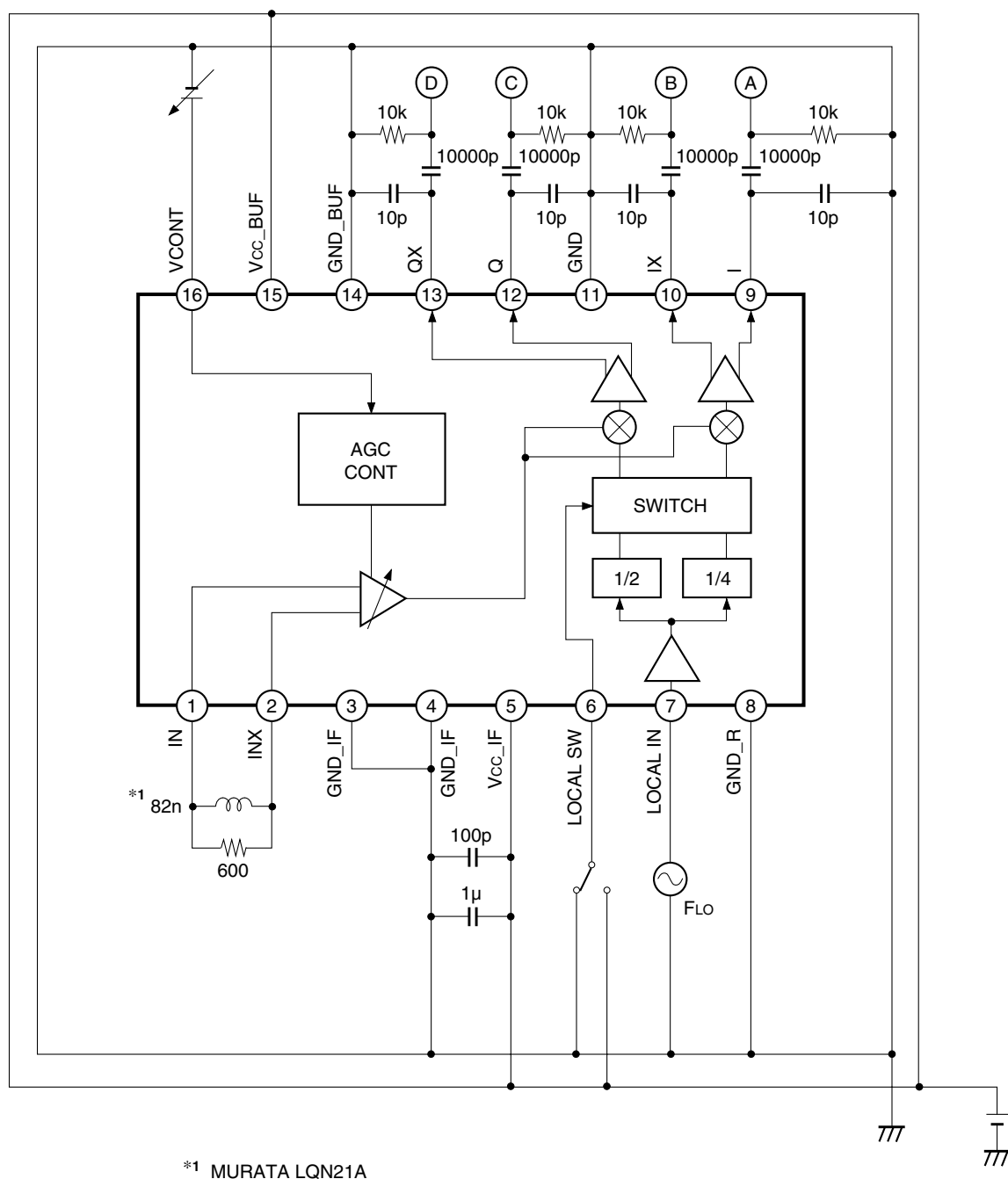
Electrical Characteristics Measurement Circuit 1



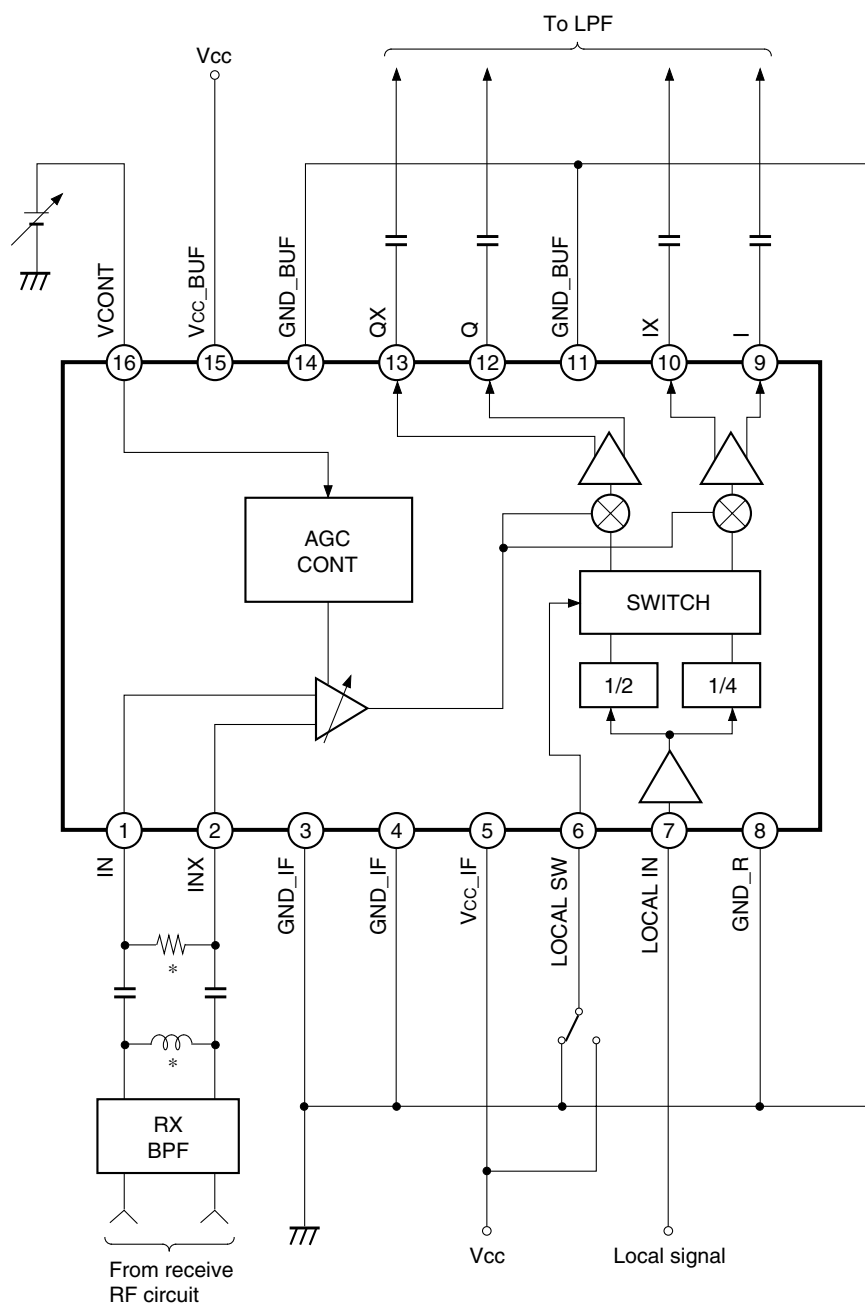
Electrical Characteristics Measurement Circuit 2



Electrical Characteristics Measurement Circuit 3



Application Circuit



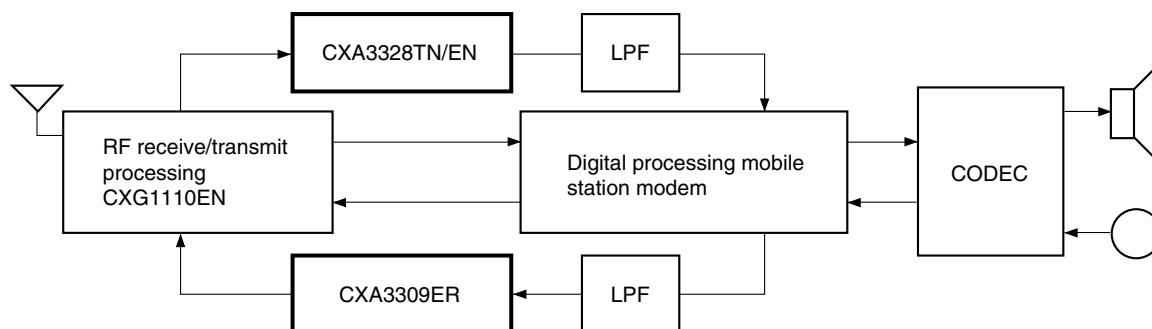
* Adjust this value so that the impedance matching with this IC is optimum.

Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

Description of Operation

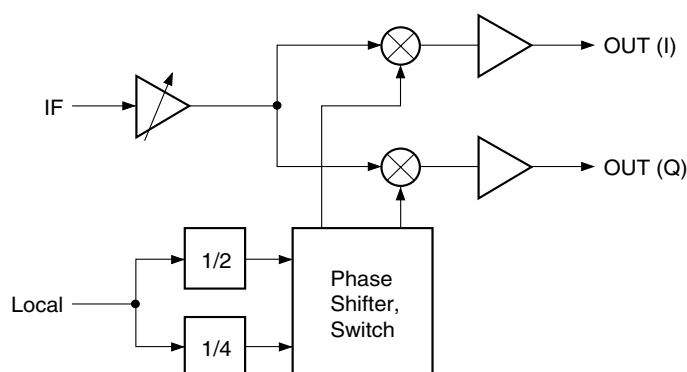
1. Outline of Operation

This IC performs the signal processing between the analog transmit baseband processing block and the analog transmit RF processing block of the cellular phone. The figure below shows the general circuit block diagram for the portable cellular phone using this IC. The input of this IC is connected to the analog RF processing block; the output is connected to the baseband signal processing block.



2. IC Internal Signal Flow

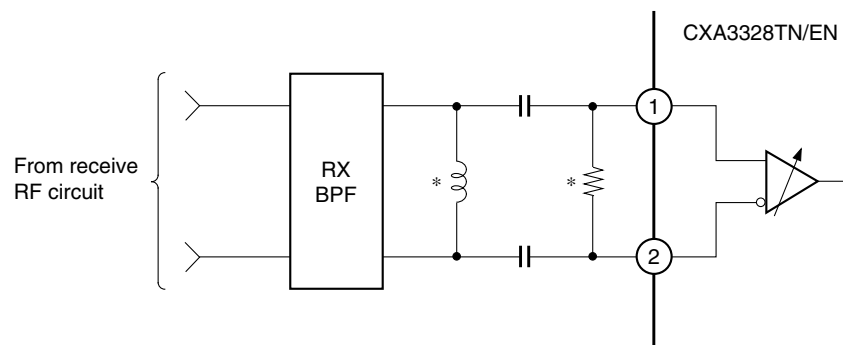
An IF signal and a local signal are input to this IC as shown in the figure below. The IF signal is gain-controlled to the necessary level by the gain control amplifier and is input to the quadrature demodulator block. The local signal is 1/2 or 1/4 frequency-divided. Also, that signal becomes the quadrature I/Q local signal via the FF phase shifter and quadrature-demodulated with the IF signal to become the baseband signal.



Notes on Operation

1. IF Input

The IF signal is differentially input to the IN pin and INX pin of this IC. IF is input to the input pin by AC coupling. The value of the AC coupling is selected so that the transfer power from the receive RF circuit is maximum.



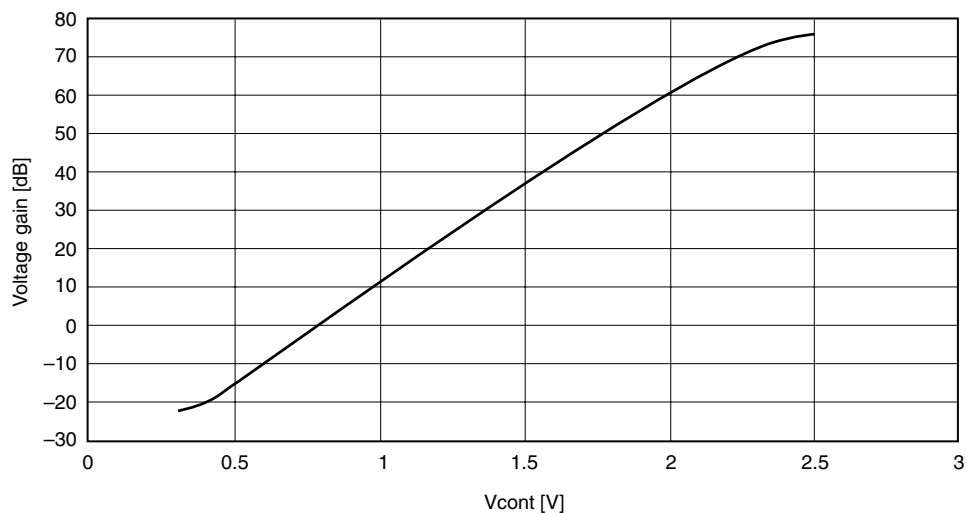
* This value must be the value taken for the optimum impedance matching between the BPF filter and this IC.

2. Notes on Power Supplies

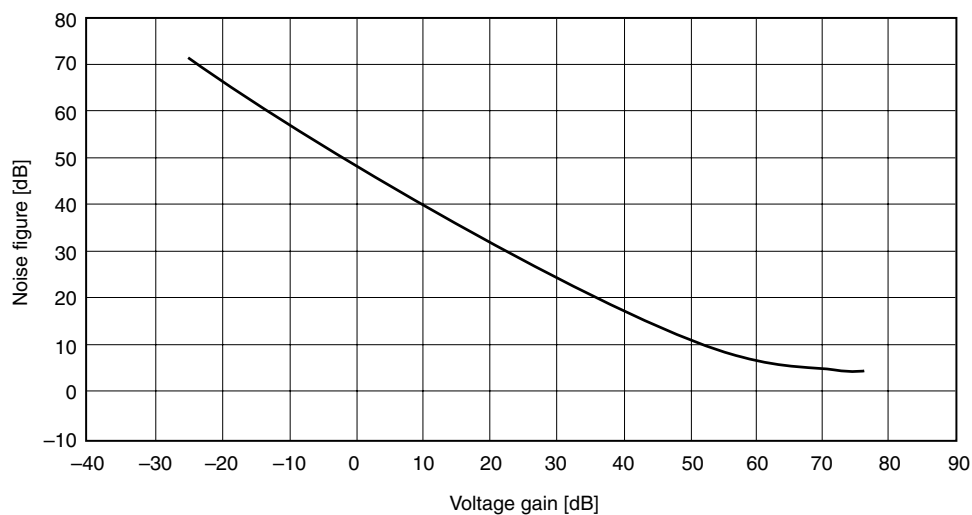
The CXA3328TN/EN is designed to operate by a 2.85V stabilized power supply to allow use with the battery driven portable phones. Using multiple voltage regulators throughout the phone is recommended to minimize the power supply noise in the CXA3328TN/EN power supply input. The recommended power supply range for the CXA3328TN/EN is 2.7 to 3.3V. Decouple the power supplies around the CXA3328TN/EN using 1 μ F capacitor for each Vcc pin. Locate this capacitor as close to the pins as possible, and minimize the series inductance for the pin connections. Using an additional 1nF decoupling capacitor in parallel to the 1 μ F capacitor is recommended to further reduce the high frequency noise in the power supply input to the CXA3328TN/EN.

Example of Representative Characteristics

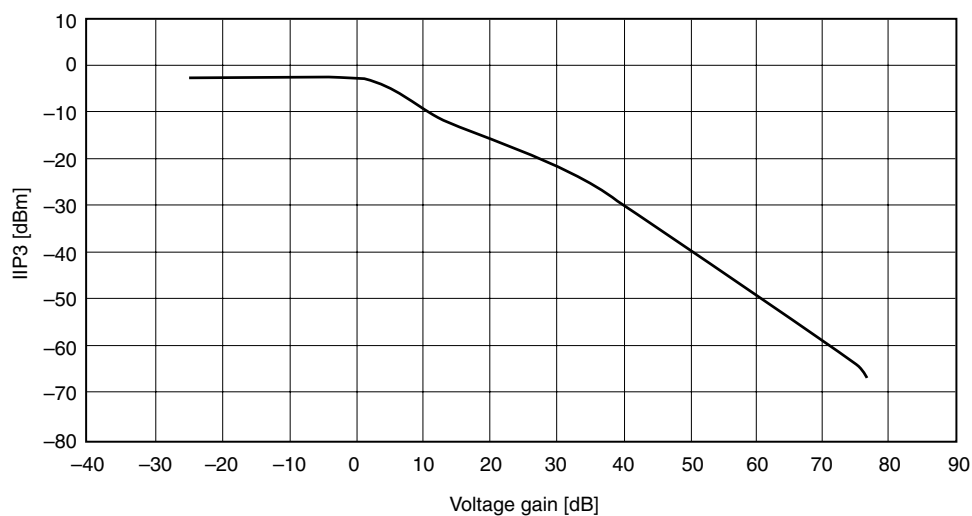
Voltage gain vs. Control voltage Vcont



Noise figure vs. Voltage gain

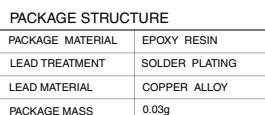


IIP3 vs. Voltage gain

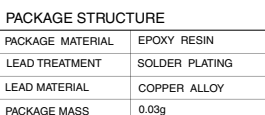


Unit: mm

16PIN TSSOP (PLASTIC)



16PIN TSSOP (PLASTIC)

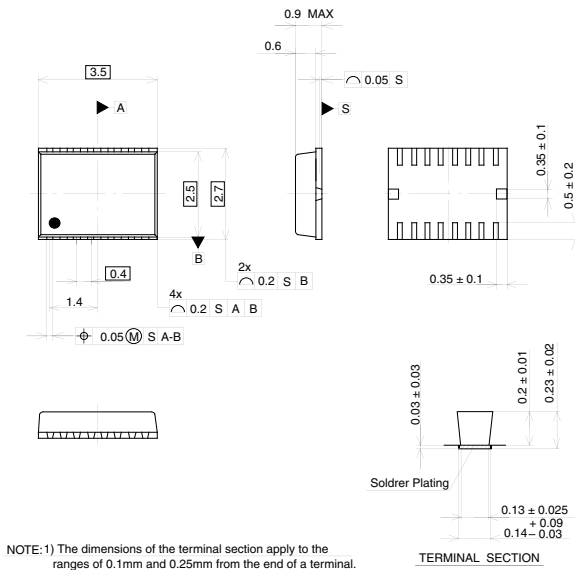


ITEM	SPEC.
LEAD MATERIAL	COPPER ALLOY
SOLDER COMPOSITION	Sn-Bi Bi:1-4wt%
PLATING THICKNESS	5-18μm

Package Outline
CXA3328EN

Unit: mm

16PIN VSON (PLASTIC)



NOTE: 1) The dimensions of the terminal section apply to the ranges of 0.1mm and 0.25mm from the end of a terminal.

TERMINAL SECTION

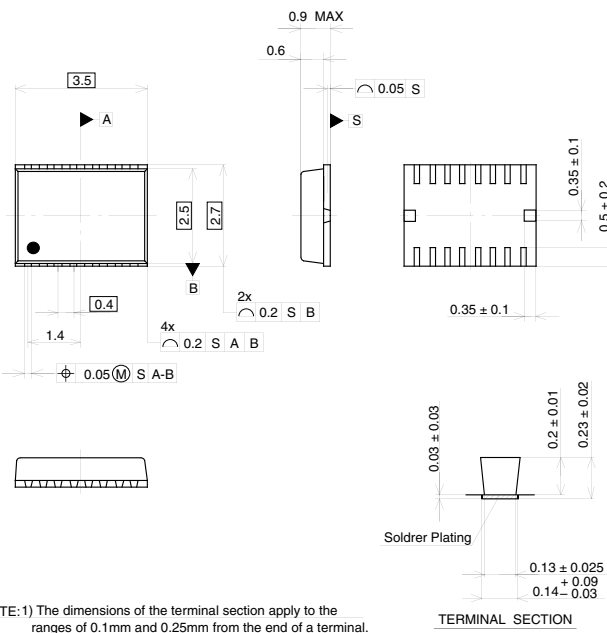
SONY CODE	VSON-16P-01
EIAJ CODE	
JEDEC CODE	

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE MASS	0.02 g

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16PIN VSON (PLASTIC)



NOTE: 1) The dimensions of the terminal section apply to the ranges of 0.1mm and 0.25mm from the end of a terminal.

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LEAD PLATING SPECIFICATIONS

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